



## ACM Research Expands into Chemical Vapor Deposition Market to Support Logic & Memory Manufacturing

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FREMONT, Calif., Dec. 12, 2022 (GLOBE NEWSWIRE) -- [ACM Research, Inc.](#) (ACM) (NASDAQ: ACMR), a leading supplier of wafer processing solutions for semiconductor and advanced wafer-level packaging (WLP) applications, today, through its operating subsidiary ACM Research (Shanghai), Inc., announced the introduction of its Ultra Pmax™ Plasma-Enhanced Chemical Vapor Deposition (PECVD) tool, marking ACM's entry into another major new product category. ACM expects to ship its first PECVD evaluation tool to a China-based customer in the next few weeks.

"Our Ultra Pmax™ PECVD tool marks expansion into another new process area of front-end semiconductor manufacturing," said Jian Wang, CEO of ACM Research (Shanghai), Inc. "Many of our customers are 28nm and above logic device providers. We anticipate a need to increase capacity at more mature nodes, as mature node production in China is significantly lower than consumption. The new PECVD tool provides ACM with another opportunity to better serve our customers while addressing the global logic and memory market. We estimate that our total addressable global market will double with the Ultra Pmax™ category announced today and the Ultra Track category announced last month."

### About ULTRA Pmax™ PECVD Tool

The ULTRA Pmax™ PECVD tool is equipped with a proprietary designed chamber, gas distribution unit and chuck, which is intended to provide better film uniformity, reduced film stress, and improved particle performance. It is available in two configurations: a one to three-chamber design that is ideal for very thin layers or fast process steps, and a four to five-chamber design that supports thick film deposition and longer process times while still optimizing throughput. Both configurations have multiple heaters per chamber for greater process control and higher productivity.

### Forward-Looking Statements

Certain statements contained in this press release are not historical facts and may be forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Forward-looking statements include statements regarding ACM's expected shipment timeline for its Ultra Pmax™ PECVD tool and ACM's estimate of the resulting increase in its total addressable market from recent new product introductions. Forward-looking statements are based on ACM management's current expectations and beliefs, and involve a number of risks and uncertainties that are difficult to predict and that could cause actual results to differ materially from those stated or implied by the forward-looking statements. Those risks and uncertainties include, but are not limited to, the following, any of which could be exacerbated even further by the continuing COVID-19 outbreak in China and globally: anticipated customer orders or identified market opportunities may not grow or develop as anticipated; customer orders already received may be postponed or canceled; ACM may be unable to obtain the qualification and acceptance of its delivered tools when anticipated or at all, which would delay or preclude ACM's recognition of revenue from the sale of those tools; suppliers may not be able to meet ACM's demands on a timely basis; ACM's technologies and tools may not gain market acceptance; ACM may be unable to compete effectively by, among other things, enhancing its existing tools, adding additional production capacity and engaging additional major customers; ACM may incur significant expenses long before it can recognize revenue from new products, if at all, due to the costs and length of research, development, manufacturing and customer evaluation process cycles; volatile global economic, market, industry and other conditions could result in sharply lower demand for products containing semiconductors and for ACM's products and in disruption of capital and credit markets; ACM's failure to successfully manage its operations, including its inability to hire, train, integrate and manage additional qualified engineers for research and development activities; and trade regulations, including those recently published by the U.S. Department of Commerce imposing certain restrictions on equipment shipments and business practices with China-based semiconductor manufacturers, currency fluctuations, political instability and war, all of which may materially and adversely affect ACM due to its substantial non-U.S. customer and supplier base and its substantial non-U.S. manufacturing operations. A further description of these risks, uncertainties and other matters can be found in filings ACM makes with the U.S. Securities and Exchange Commission. Because forward-looking statements involve risks and uncertainties, actual results and events may differ materially from results and events currently expected by ACM. ACM undertakes no obligation to publicly update these forward-looking statements to reflect events or circumstances that occur after the date hereof or to reflect any change in its expectations with regard to these forward-looking statements or the occurrence of unanticipated events.

### About ACM Research, Inc.

ACM develops, manufactures and sells semiconductor process equipment for single-wafer or batch wet cleaning, electroplating, stress-free polishing, vertical furnace processes, and track for coating and developing which are critical to advanced

semiconductor device manufacturing and wafer-level packaging. The company is committed to delivering customized, high-performance, cost-effective process solutions that semiconductor manufacturers can use in numerous manufacturing steps to improve productivity and product yield. For more information, visit [www.acmrcsh.com](http://www.acmrcsh.com).

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